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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/804,903	03/19/2004	Michael Keat Lye Lee	111079-134717	8363
25943 7590 10/02/2007 SCHWABE, WILLIAMSON & WYATT, P.C. PACWEST CENTER, SUITE 1900 1211 SW FIFTH AVENUE PORTLAND, OR 97204			EXAMINER NGO, HUNG V	
			ART UNIT 2831	PAPER NUMBER
			MAIL DATE 10/02/2007	DELIVERY MODE PAPER

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

## Office Action Summary

Application No.

10/804,903

Applicant(s)

LEE ET AL.

Examiner

Hung V. Ngo

Art Unit

2831

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 12 July 2007.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-28 is/are pending in the application.
- 4a) Of the above claim(s) 11-15 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-10, 16-28 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)          | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____                                      |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)          | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date _____  | 6) <input type="checkbox"/> Other: _____                          |

## DETAILED ACTION

### *Claim Rejections - 35 USC § 102*

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-3, 10 are rejected under 35 U.S.C. 102(b) as being anticipated by Banks et al (US 6,015,722).

Re claim 1, Banks et al disclose an apparatus (as best shown in Fig 9), comprising:

a die carrier (512) having a surface;

a heat spreader lid (532)(col. 27, line 65-68) having a surface parallel to the surface of the die carrier, the heat spreader lid mounted on the die carrier to form a lid cavity (530) (Fig 9);

an integrated circuit die (518) mounted on the die carrier and within the lid cavity; and

a cured mold compound (Fig 7, step 320, 330) disposed to fill the lid cavity and to at least partially surround the IC die, the cured mold compound being in contact with the surface of the die carrier and the surface of the heat spreader lid (Fig 9).

Re claim 2, wherein the heat spreader lid has a dispensing hole (544) formed therein to facilitate injection of a mold compound solution into the lid cavity and an air

outlet hole (546) formed therein to allow air to escape from the lid cavity (col. 27, lines 45-50).

Re claim 3, wherein heat spreader lid is made of metal (col. 35, line 4-6).

Re claim 10, wherein the mold compound is a polymeric material (epoxy)(col. 28, lines 16-18).

***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 4-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Banks et al in view of Applicant Admitted Prior Art (AAPA)

Re claim 7, wherein the die (518) includes a first surface, a second surface and a plurality of lateral sides extending between the first and second surfaces (Fig 9); the first surface includes a plurality of electrical contacts (520) coupled to the die carrier; and the mold compound extends between the heat spreader lid and the die carrier and surrounds the lateral sides and the first surface of the die (Fig 9).

Re claim 8, wherein the die is mounted to the die carrier by a flip-chip mounting (Fig 9).

Re claim 9, wherein the flip-chip mounting includes a plurality of solder bumps (520) coupling the die to the die carrier.

The teaching as discussed above does not disclose the heat spreader lid including a thermal interface material interposed in thermal conducting relationship between the heat spreader lid and the die (re claim 4), wherein the thermal interface material is coaxially aligned with the die and includes a width and a length dimension which are substantially the same as a corresponding width and a corresponding length dimension of the die (re claim 5), wherein the thermal interface material comprises a cold form thermal interface material (re claim 6), the second surface is disposed in an abutting relationship with the thermal interface material (re claim 7).

AAPA teaches the use of a thermal interface material (22) interposed in thermal conducting relationship between the heat spreader lid and the die (Fig 1), wherein the thermal interface material is coaxially aligned with the die and includes a width and a length dimension which are substantially the same as a corresponding width and a corresponding length dimension of the die (Fig 1), wherein the thermal interface material comprises a cold form thermal interface material being known, the second surface is disposed in an abutting relationship with the thermal interface material (Fig 1)

It would have been obvious to one of ordinary skill in the art at the time the invention was made to include the thermal interface with the structure of banks et al for the purpose of enhancing heat remover

Claims 16-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Banks et al in view of Low et al (US 6,404,626).

Re claim 16, Banks et al disclose a system, comprising:  
an integrated circuit (IC) package including a die carrier (512); a heat spreader lid

(532)(col. 27, lines 65-68) mounted on the die carrier to form a lid cavity (530)(Fig 9); an IC die (518) mounted on the die carrier and within the lid cavity; and a cured mold compound (Fig 7, step 320, 330) disposed to fill the lid cavity and to partially surround the IC die (Fig 9);

A circuit board or a mother board (540) having mounted thereon the IC package

Re claim 20, wherein the heat spreader lid has a dispensing hole (544) formed therein to facilitate injection of a mold compound solution into the lid cavity and an air outlet hole (546) formed therein to allow air to escape from the lid cavity (col. 27, lines 45-50).

Re claim 21, wherein heat spreader lid is made of metal (col. 35, lines 4-6).

The teaching as discussed above does not disclose a dynamic random access memory coupled to the IC package; and an input/output interface coupled to the IC package (re claims 16), the IC die being a microprocessor (re claim 17), wherein the input/output interface comprises a networking interface (re claim 18), wherein the system is a selected one of a set-top box, an entertainment unit and a DVD player (re claim 19).

Re claims 16-19, Low et al disclose a circuit board or mother board (100) having mounted thereon the IC package (CPU 102); a dynamic random access memory (106) coupled to the IC package, the IC die being a microprocessor (CPU 102) and an input/output interface (27) coupled to the IC package, wherein the input/output interface comprises a networking interface (75), wherein the system is a selected one of a set-top box, an entertainment unit and a DVD player (Fig 1a)(re claim 19).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to include the dynamic random access memory coupled to the IC package; and the input/output interface or networking interface coupled to the IC package, the set-top box with the structure of Banks et al for the purpose of making a personal computer

Claims 22-28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Banks et al in view of Low et al as applied to claims 16, 20, 21 above, and further in view of Applicant Admitted Prior Art (AAPA)

Re claim 25, wherein the die (518) includes a first surface, a second surface and a plurality of lateral sides extending between the first and second surfaces (Fig 9); the first surface includes a plurality of electrical contacts (520) coupled to the die carrier; and the mold compound extends between the heat spreader lid and the die carrier and surrounds the lateral sides and the first surface of the die (Fig 9).

Re claim 26, wherein the die is mounted to the die carrier by a flip-chip mounting (Fig 9).

Re claim 27, wherein the flip-chip mounting includes a plurality of solder bumps (520) coupling the die to the die carrier.

Re claim 28, wherein the mold compound is a polymeric material (epoxy)(col. 28, lines 16-18).

The teaching as discussed above does not disclose the heat spreader lid including a thermal interface material interposed in thermal conducting relationship between the heat spreader lid and the die (re claim 22), wherein the thermal interface

material is coaxially aligned with the die and includes a width and a length dimension which are substantially the same as a corresponding width and a corresponding length dimension of the die (re claim 23), wherein the thermal interface material comprises a cold form thermal interface material (re claim 24), the second surface is disposed in an abutting relationship with the thermal interface material (re claim 25).

AAPA teaches the use of a thermal interface material (22) interposed in thermal conducting relationship between the heat spreader lid and the die (Fig 1), wherein the thermal interface material is coaxially aligned with the die and includes a width and a length dimension which are substantially the same as a corresponding width and a corresponding length dimension of the die (Fig 1), wherein the thermal interface material comprises a cold form thermal interface material is known (a response 07-12-07), the second surface is disposed in an abutting relationship with the thermal interface material (Fig 1)

It would have been obvious to one of ordinary skill in the art at the time the invention was made to include the thermal interface with the structure of the modified banks et al for the purpose of enhancing heat remover

### ***Response to Arguments***

Applicant's arguments with respect to claims 1, 16 have been considered but are moot in view of the new ground(s) of rejection.

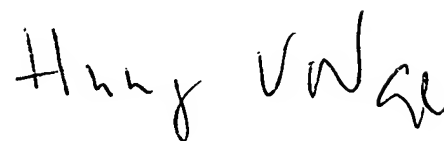


Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hung V. Ngo whose telephone number is (571) 272-1979. The examiner can normally be reached on Monday to Thursday 8:30-6:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Dean A. Reichard can be reached on (571) 272-2800 EXT 31. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

HVN  
09-20-07



**HUNG V. NGO**  
**PRIMARY EXAMINER**